# AUIRG4BC30S-S

### AUIRG4BC30S-SL Standard Speed IGBT

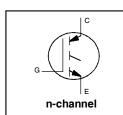
### **INSULATED GATE BIPOLAR TRANSISTOR**

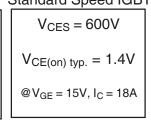
#### **Features**

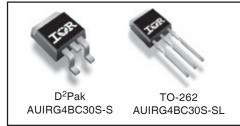
- Standard: optimized for minimum saturation voltage and low operating frequencies (< 1kHz)</li>
- · Lead-Free, RoHS Compliant
- Automotive Qualified \*

#### **Benefits**

 Typical Applications: PTC Heater, Discharge Switch & Relay Replacements







G	С	E
Gate	Collector	Emitter

### **Absolute Maximum Ratings**

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only; and functional operation of the device at these or any other condition beyond those indicated in the specifications is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability. The thermal resistance and power dissipation ratings are measured under board mounted and still air conditions. Ambient temperature  $(T_A)$  is 25°C, unless otherwise specified

	Parameter	Max.	Units
V <sub>CES</sub>	Collector-to-Emitter Breakdown Voltage	600	V
I <sub>C</sub> @ T <sub>C</sub> = 25°C	Continuous Collector Current	34	
I <sub>C</sub> @ T <sub>C</sub> = 100°C	Continuous Collector Current	18	Α
I <sub>CM</sub>	Pulsed Collector Current ①	68	
$I_{LM}$	Clamped Inductive Load Current ②	68	
$V_{GE}$	Gate-to-Emitter Voltage	±20	V
E <sub>ARV</sub>	Reverse Voltage Avalanche Energy ③	10	mJ
P <sub>D</sub> @ T <sub>C</sub> = 25°C	Maximum Power Dissipation	100	w
P <sub>D</sub> @ T <sub>C</sub> = 100°C	Maximum Power Dissipation	42	
T <sub>J</sub>	Operating Junction and	-55 to +150	
T <sub>STG</sub>	Storage Temperature Range		∞
	Soldering Temperature, for 10 seconds	300 (0.063 in. (1.6mm) from case )	7

#### **Thermal Resistance**

	Parameter	Тур.	Max.	Units
R <sub>eJC</sub>	Junction-to-Case		1.2	
R <sub>0CS</sub>	Case-to-Sink, Flat, Greased Surface	0.50		°C/W
$R_{\theta JA}$	Junction-to-Ambient, typical socket mount		40	
Wt	Weight	1.44		g (oz)

<sup>\*</sup> When mounted on 1" square PCB (FR-4 or G-10 Material ). For recommended footprint and soldering techniques refer to application note #AN-994.

### Electrical Characteristics @ T<sub>J</sub> = 25°C (unless otherwise specified)

	Parameter	Min.	Тур.	Max.	Units	Conditions
V <sub>(BR)CES</sub>	Collector-to-Emitter Breakdown Voltage	600	_	_	V	$V_{GE} = 0V, I_C = 250\mu A$
V <sub>(BR)ECS</sub>	Emitter-to-Collector Breakdown Voltage 4	18	_	_	V	$V_{GE} = 0V, I_{C} = 1.0A$
$\Delta V_{(BR)CES}/\Delta T_J$	Temperature Coeff. of Breakdown Voltage	_	0.75	_	V/°C	$V_{GE} = 0V$ , $I_C = 1.0mA$
		_	1.40	1.6		$I_C = 18A$ $V_{GE} = 15V$
V <sub>CE(ON)</sub>	Collector-to-EmitterSaturationVoltage	_	1.84	_	V	I <sub>C</sub> = 34A See Fig. 2, 5
		_	1.45	_	"	I <sub>C</sub> = 18A , T <sub>J</sub> = 150°C
V <sub>GE(th)</sub>	GateThresholdVoltage	3.0	_	6.0		$V_{CE} = V_{GE}$ , $I_C = 250\mu A$
$\Delta V_{GE(th)}/\Delta T_J$	Temperature Coeff. of Threshold Voltage	_	-11	_	mV/°C	$V_{CE} = V_{GE}$ , $I_C = 250\mu A$
g <sub>fe</sub>	Forward Transconductance ®	6.0	11	_	S	V <sub>CE</sub> = 100V, I <sub>C</sub> = 18A
I <sub>CES</sub>	Zero Gate Voltage Collector Current	_	_	250	μΑ	$V_{GE} = 0V, V_{CE} = 600V$
ICES	2010 date voltage concetor current		_	2.0	μ, (	$V_{GE} = 0V, V_{CE} = 10V, T_J = 25^{\circ}C$
			_	1000		$V_{GE} = 0V$ , $V_{CE} = 600V$ , $T_J = 150$ °C
I <sub>GES</sub>	Gate-to-Emitter Leakage Current	_	_	±100	nA	$V_{GE} = \pm 20V$

### Switching Characteristics @ $T_J = 25$ °C (unless otherwise specified)

	Parameter	Min.	Тур.	Max.	Units	Conditions
Qg	Total Gate Charge (turn-on)	_	50	75		I <sub>C</sub> = 18A
Q <sub>ge</sub>	Gate - Emitter Charge (turn-on)	_	7.3	11	nC	V <sub>CC</sub> = 400V See Fig. 8
Q <sub>gc</sub>	Gate - Collector Charge (turn-on)	_	17	26		$V_{GE} = 15V$
t <sub>d(on)</sub>	Turn-On Delay Time	_	22	_		
t <sub>r</sub>	Rise Time	_	18	_	ns	$T_J = 25^{\circ}C$
t <sub>d(off)</sub>	Turn-Off Delay Time	_	540	810	113	$I_C = 18A, V_{CC} = 480V$
t <sub>f</sub>	Fall Time	_	390	590		$V_{GE} = 15V$ , $R_G = 23\Omega$
Eon	Turn-On Switching Loss	_	0.26	_		Energy losses include "tail"
E <sub>off</sub>	Turn-Off Switching Loss	_	3.45	_	mJ	See Fig. 9, 10, 14
Ets	Total Switching Loss	_	3.71	5.6		
t <sub>d(on)</sub>	Turn-On Delay Time	_	21	_		$T_{J} = 150^{\circ}C,$
t <sub>r</sub>	Rise Time	_	19	_	ns	$I_C = 18A, V_{CC} = 480V$
t <sub>d(off)</sub>	Turn-Off Delay Time	_	790		115	$V_{GE} = 15V$ , $R_G = 23\Omega$
t <sub>f</sub>	Fall Time	_	760	_		Energy losses include "tail"
E <sub>ts</sub>	Total Switching Loss	_	6.55	_	mJ	See Fig. 11, 14
LE	Internal Emitter Inductance	_	7.5	_	nH	Measured 5mm from package
C <sub>ies</sub>	Input Capacitance	_	1100			$V_{GE} = 0V$
Coes	Output Capacitance	_	72	_	рF	V <sub>CC</sub> = 30V See Fig. 7
C <sub>res</sub>	Reverse Transfer Capacitance	_	13	_		f = 1.0MHz

#### Notes:

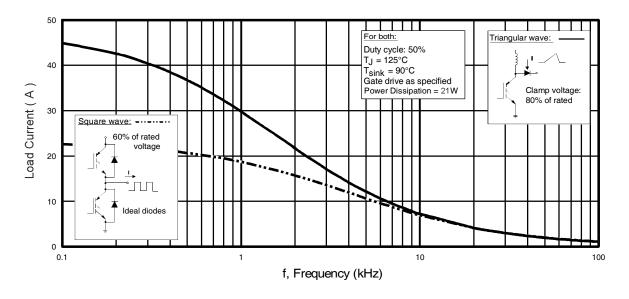
- $\odot$  Repetitive rating;  $V_{GE} = 20V$ , pulse width limited by max. junction temperature (See fig. 13b).
- $@~V_{CC}$  = 80%(V\_{CES}), V\_{GE} = 20V, L = 10µH, R\_G = 23 $\Omega$ , (See fig. 13a).
- 3 Repetitive rating; pulse width limited by maximum junction temperature.
- 4 Pulse width  $\leq 80\mu s$ ; duty factor  $\leq 0.1\%$ .
- ⑤ Pulse width 5.0µs, single shot.

### Qualification Information<sup>†</sup>

		Automotive  (per AEC-Q101) ††			
Qualification L	evel	Comments: This part number(s) passed Automotive qualification. IR's Industrial and Consumer qualification level is granted by extension of the higher Automotive level.			
		D <sup>2</sup> PAK	MSL1 †††		
Moisture Sensitivity Level			(per IPC/JEDEC J-STD-020)		
		TO-262	N/A		
	Machine Model		Class M4 (400V)		
		AEC-Q101-002			
505	Human Body Model	Class H1C (2000V)			
ESD		AEC-Q101-001			
	Charged Device Model	Class C5 (1000V)			
			AEC-Q101-005		
RoHS Compliant		Yes			

 $<sup>\ \, \ \, \</sup>text{$\uparrow$ Qualification standards can be found at International Rectifier's web site: } \underline{\text{$http://www.irf.com}}$ 

<sup>††</sup> Exceptions to AEC-Q101 requirements are noted in the qualification report.



**Fig. 1** - Typical Load Current vs. Frequency (Load Current = I<sub>RMS</sub> of fundamental)

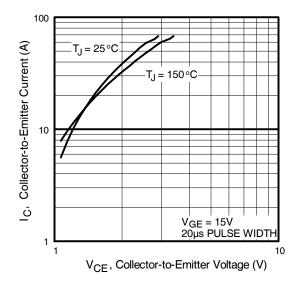


Fig. 2 - Typical Output Characteristics 4

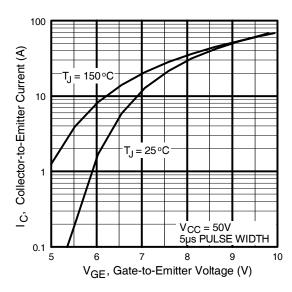
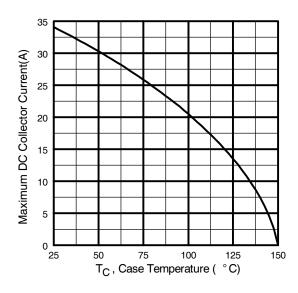


Fig. 3 - Typical Transfer Characteristics www.irf.com



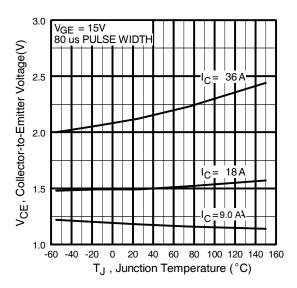


Fig. 4 - Maximum Collector Current vs. Case Temperature

Fig. 5 - Typical Collector-to-Emitter Voltage vs. Junction Temperature

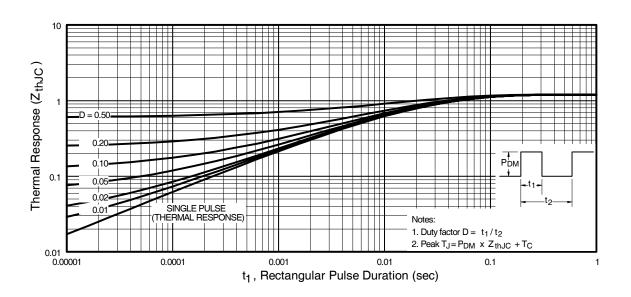
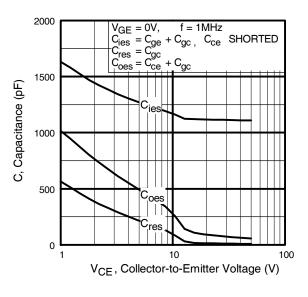
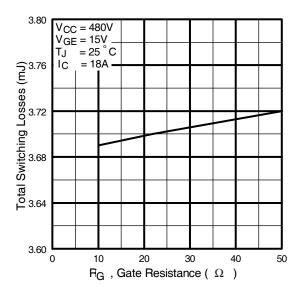


Fig. 6 - Maximum Effective Transient Thermal Impedance, Junction-to-Case



**Fig. 7 -** Typical Capacitance vs. Collector-to-Emitter Voltage

**Fig. 8** - Typical Gate Charge vs. Gate-to-Emitter Voltage



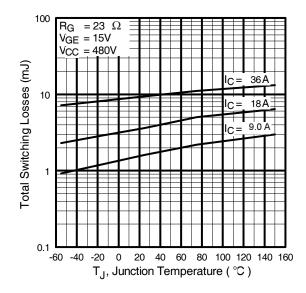
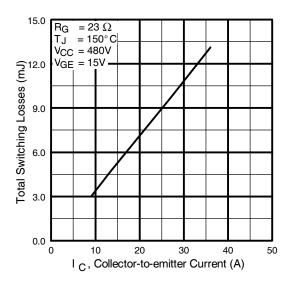


Fig. 9 - Typical Switching Losses vs. Gate Resistance

Fig. 10 - Typical Switching Losses vs. Junction Temperature

6



**Fig. 11 -** Typical Switching Losses vs. Collector-to-Emitter Current

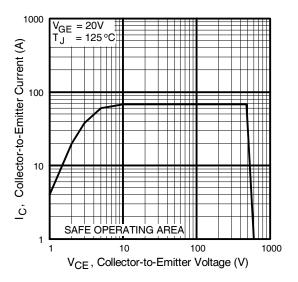
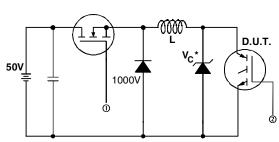


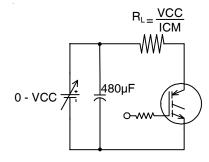
Fig. 12 - Turn-Off SOA



\* Driver same type as D.U.T.; Vc = 80% of Vce(max)

\* Note: Due to the 50V power supply, pulse width and inductor will increase to obtain rated ld.

Fig. 13a - Clamped Inductive Load Test Circuit



Pulsed Collector Current Test Circuit

Fig. 13b - Pulsed Collector Current Test Circuit

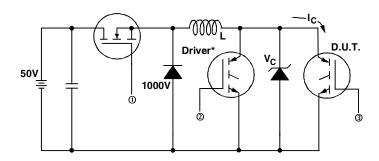


Fig. 14a - Switching Loss Test Circuit

\* Driver same type as D.U.T., VC = 480V

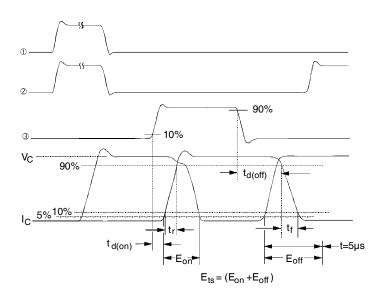
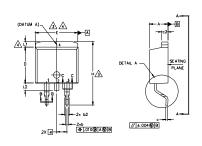


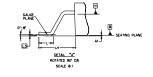
Fig. 14b - Switching Loss Waveforms

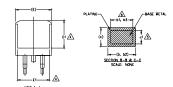
## D<sup>2</sup>Pak (TO-263AB) Package Outline

Dimensions are shown in millimeters (inches)









- 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994
- 2. DIMENSIONS ARE SHOWN IN MILLIMETERS [INCHES].
- 3. DIMENSION D & E DO NOT INCLUDE MOLD FLASH, MOLD FLASH SHALL NOT EXCEED 0.127 [.005"] PER SIDE. THESE DIMENSIONS ARE MEASURED AT THE OUTMOST EXTREMES OF THE PLASTIC BODY AT DATUM H.
- 4. THERMAL PAD CONTOUR OPTIONAL WITHIN DIMENSION E, L1, D1 & E1.
- 5. DIMENSION 61 AND c1 APPLY TO BASE METAL ONLY.
- 6. DATUM A & B TO BE DETERMINED AT DATUM PLANE H.
- 7, CONTROLLING DIMENSION; INCH.
- 8. OUTLINE CONFORMS TO JEDEC OUTLINE TO-263AB

S Y M B O L		Ň			
B	MILLIMETERS		INC	NOT EV	
Ĺ	MIN.	MAX.	MIN.	MAX.	Š
Α	4.06	4.83	.160	.190	
Α1	0.00	0.254	.000	.010	
b	0.51	0.99	.020	.039	
ь1	0.51	0.89	.020	.035	5
b2	1,14	1.78	.045	.070	
b3	1,14	1,73	.045	.068	5
С	0.38	0.74	.015	.029	
с1	0,38	0.58	.015	.023	5
c2	1,14	1.65	.045	,065	
D	8.38	9.65	.330	.380	3
D1	6.86	-	.270		4
Ε	9.65	10,67	.380	.420	3,4
E1	6.22	-	.245		4
е	2.54	BSC	.100	BSC	
Н	14,61	15,88	.575	.625	
L	1.78	2.79	.070	.110	
L1	-	1,65	-	.066	4
L2	1,27	1.78	-	.070	
L3	0.25	BSC	.010	BSC	
L4	4,78	5.28	.188	.208	

#### LEAD ASSIGNMENTS

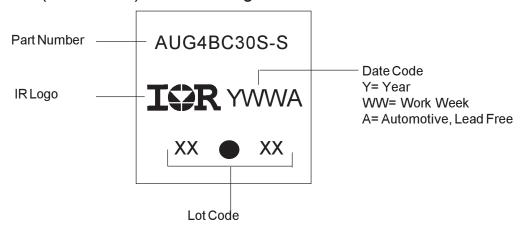
### **HEXFET** 1.- GATE 2. 4.- DRAIN 3.- SOURCE

### IGBTs. CoPACK 1.- GATE 2, 4.- COLLECTOR 3.- EMITTER

#### DIODES

- \* PART DEPENDENT.

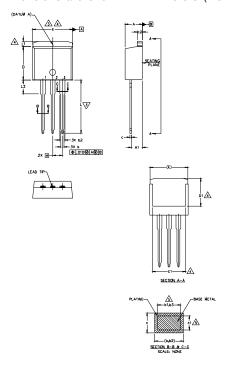
## D<sup>2</sup>Pak (TO-263AB) Part Marking Information



Note: For the most current drawing please refer to IR website at http://www.irf.com/package/ www.irf.com

### TO-262 Package Outline

Dimensions are shown in millimeters (inches)



#### MOTES

- 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994
- 2. DIMENSIONS ARE SHOWN IN MILLIMETERS [INCHES].
- (3) DIMENSION D & E DO NOT INCLUDE MOLD FLASH, MOLD FLASH SHALL NOT EXCEED 0.127 [.005] PER SIDE. THESE DIMENSIONS ARE MEASURED AT THE OUTMOST EXTREMES OF THE PLASTIC BODY.
- 4 THERMAL PAD CONTOUR OPTIONAL WITHIN DIMENSION E, L1, D1 & E1.
- 5 DIMENSION 61 AND 61 APPLY TO BASE METAL ONLY.
- 6. CONTROLLING DIMENSION; INCH.
- 7.— OUTLINE CONFORM TO JEDEC TO-262 EXCEPT A1(max.), b(min.) AND D1(min.) WHERE DIMENSIONS DERIVED THE ACTUAL PACKAGE OUTLINE.

S		DIMENSIONS				
B O	MILLIM	ETERS	INC	NOT ES		
Ľ	MIN.	MAX.	MIN.	MAX.	S	
Α	4,06	4.83	.160	.190		
A1	2.03	3.02	.080	.119		
ь	0.51	0.99	.020	.039		
ь1	0.51	0,89	.020	,035	5	
b2	1.14	1.78	.045	.070		
ь3	1,14	1.73	.045	.068	5	
С	0.38	0.74	.015	.029		
c1	0.38	0.58	.015	.023	5	
c2	1,14	1.65	.045	.065		
D	8,38	9,65	.330	,380	3	
D1	6,86	-	.270	-	4	
Ε	9.65	10.67	.380	.420	3,4	
E1	6,22	-	.245		4	
e	2.54	BSC	.100 BSC			
L	13.46	14.10	.530	.555		
L1	-	1,65	-	.065	4	
L2	3.56	3.71	.140	.146		

#### LEAD ASSIGNMENTS

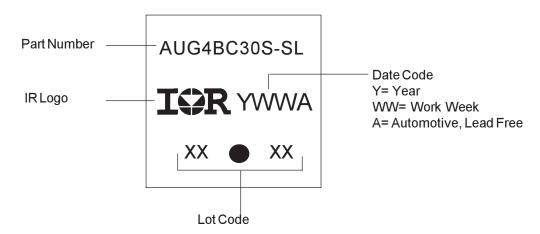
#### HEXFET

- 1.- GATE 2.- DRAIN
- 3.- SOURC 4.- DRAIN

#### IGBTs, CoPACK

1.- GATE
2.- COLLECTOR
3.- EMITTER
4.- COLLECTOR

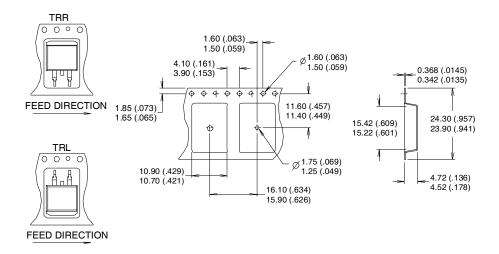
### TO-262 Part Marking Information

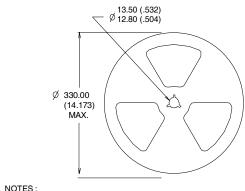


Note: For the most current drawing please refer to IR website at <a href="http://www.irf.com/package/">http://www.irf.com/package/</a>

# D<sup>2</sup>Pak Tape & Reel Information

Dimensions are shown in millimeters (inches)





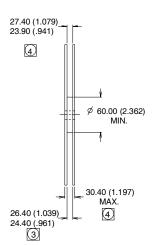


- COMFORMS TO EIA-418.

  CONTROLLING DIMENSION: MILLIMETER.

  DIMENSION MEASURED @ HUB.

  INCLUDES FLANGE DISTORTION @ OUTER EDGE.



**Ordering Information** 

Base part number	Package	Standard Pack		Complete Part Number
		Form	Quantity	
AUIRG4BC30S-SL	TO-262	Tube	50	AUIRG4BC30S-SL
AUIRG4BC30S-S	D2Pak	Tube	50	AUIRG4BC30S-S
		Tape and Reel Left	800	AUIRG4BC30SSTRL
		Tape and Reel Right	800	AUIRG4BC30SSTRR

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